



AMENDMENTS TO THE SPECIFICATION

Please amend the paragraph beginning at page 4, line 28, as follows:

Possible substrates for circuit board 11 include a heat-resistant substrate made of epoxy resin including glass fiber, or a ceramic plate, and a polymeric resin sheet including a film sheet made of polyethylene terephthalate (PET) resin, acrylnitrile-butadiene-styrene (ABS) resin, or polycarbonate resin, ~~or polyimide resin~~. Any material used for a general circuit board is applicable. Especially preferable is a polymeric resin sheet made of PET resin, ABS resin, polycarbonate resin, ~~polyimide resin~~, or the like. Because such polymeric resin sheets find a wide variety of applications as general-purpose plastic, they are inexpensive. Additionally, because circuit board 11 can be formed to have a thickness ranging from approximately 50 to 400 μm , such polymeric resin sheets are effective in reducing a thickness of electronic circuit devices.

Please insert the following paragraph at page 7, line 24:

As shown in Figs. 1 - 2A, a cross-sectional size of the connection terminal 16 is less than a corresponding cross-sectional size of the through-hole 14, and the corresponding cross-sectional size of the through-hole is less than a corresponding cross-sectional size of the electrode pad 12, with the corresponding cross-sectional size of the electrode pad being at least twice as large as a the cross-sectional size of the connection terminal.